



SPEC NO.: SRD-002L

# **SPECIFICATION**

**TO:STE996** 

Model Name: SAW Resonator **PART NO: SSR304.30N01F11** CUSTOMER PART NO.:

## STRONG ELECTRONICS&TECHNOLOGY LIMITED

# 深圳市思硕电子科技有限公司

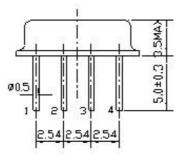
Service Hotline:400-601-8985 Fax: 86 755 84528986 Email:info@strongelectronics.net www.sawfilter.cn

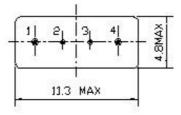


# 1. Package Dimension

(F11) Unit: mm









Pin No.	Function		
Pin 1	Input		
Pin 4	Output		
Pin 2.3	Ground		

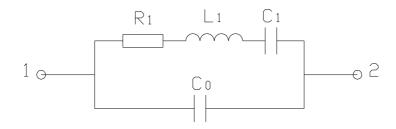
# 2. Marking

SSR304.30 N01

- 1. Black Ink Marking S:STRONG
- 2. SR304.30: Product Code
- 3. N01: One-port SAW Resonator,+/-75K
- 4. 304.30: Center Frequency



# 3. Equivalent LC Model



## 4. Performance

# 4.1 Maximum Rating

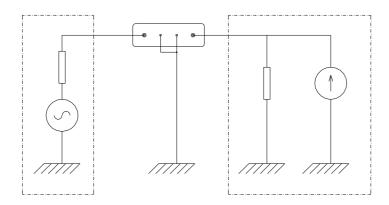
Item	Value		
Operation Temperature Range	-40 to +80		
Storage Temperature Range	-45 to +85		
DC Voltage	10V		
Source Power	0 dBm		

## 4.2 Electronic Characteristics

Item	Units	Minimum	Typical	Maximum
Center Frequency (fo)	MHz	304.225	304.30	304.375
Insertion Loss	dB	_	1.5	2.0
Quality Factor				
Unloaded Q	_	_	11,000	_
50Ω Loaded Q	_	_	2,000	_
Temperature Stability				
Turnover Temperature		_	25	_
Freq. Temp. Coefficient	ppm/		0.032	_
Frequency Aging	ppm/yr	_	<±10	_
DC Insulation Resistance	МΩ	1.0	_	_
RF Equivalent RLC Model				
Motional Resistance R1	Ω	_	18	26
Motional Inductance L1	μH	_	86	_
Motional Capacitance C1	fF	_	1.56	_
Shunt Static Capacitance C0	pF	1.7	2.0	2.3



### 4.3 Test Circuit



Note: Reference temperature shall be  $25\pm2^{\circ}$ C. However, the measurement may be carried out at  $5^{\circ}$ C to  $35^{\circ}$ C unless there is a dispute.

## 5. Reliability

### 5.1 Resistance to Soldering heat:

- 5.1.1 The components shall remain within the electrical specifications after it soldered on the 1mm-thickness PCB board and dipped in the solder at 260°C±5°C for 10±1 seconds.
- 5.1.2 The components shall remain within the electrical specifications after it soldered by electric iron, solder at 350°C±10°C for 3~4 seconds, recovery time : 2h±0.5h.

### 5.2 Thermal Shock:

The components shall remain within the electrical specifications after being kept at the condition of heat cycle conditions: TA=-40 $^{\circ}$ C±3 $^{\circ}$ C, TB=85 $^{\circ}$ C±2 $^{\circ}$ C, t1=t2=30min, switch time≤3min & cycle time : 100 times, recovery time : 2h±0.5h.

## 5.3 The Temperature Storage:

- 5.3.1 High Temperature Storage: The components shall remain within the electrical specifications after being kept at the 85°C±2°Cfor 500 hours, recovery time: 2h±0.5h.
- 5.3.2 Low Temperature Storage: The components shall remain within the electrical specifications after being kept at the -40°C±3°C for 500 hours, recovery time: 2h±0.5h.

### 5.4 Humidity test:

The components shall remain within the electrical specifications after being kept at the condition of ambient temperature 60°C±2°C, and 90~95% RH for 500 hours.

#### 5.5 Drop test:

The components shall remain within the electrical specifications after random free drops 10 times from height of 1.0 meter onto concrete floor, and the specimens shall meet the electrical



specifications in table 5, external visual inspection.

### 5.6 Solderability test:

at the condition of temperature 245  $^{\circ}$ C  $\pm 5^{\circ}$ C Depth: DIP 2/3 , SMD 1/5, time: 3.0s-5.0s, 80% or more of the immersed surface shall be covered with solder and well-proportioned.

## 5.7 Vibration Fatigue:

The components shall remain within the electrical specifications after loaded vibration at 10~55Hz, amplitude 1.5mm, X, Y, Z, direction, for 2 hours.

## 5.8Terminal strength:

The force 10±1 seconds of 19.6N is applied to each terminal, and 45° in the same direction 2 times with 2N bending force (Exception: SMD)

#### 5.9 Mechanical Shock:

The components shall remain within the electrical specifications after 1000 shocks, acceleration 392 m/s<sup>2</sup>, duration 6ms.

Note: As a result of the particularity of inner structure of SAW products, it easy to be breakdown by electrostatic, so we should pay attention to ESD protect in the test.

#### 6. Remarks

#### 6.1 Static voltage

Static voltage between signal load & ground may cause deterioration & destruction of the component. Please avoid static voltage.

#### 6.2 Ultrasonic cleaning

Ultrasonic vibration may cause deterioration & destruction of the component. Please avoid ultrasonic cleaning.

## 6.3 Soldering

Only leads of component may be soldered. Please avoid soldering another part of component.

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